

[삼성전자]DS부문 S.LSI사업부 박사졸업자(졸업예정자) 채용공고

■ 회사소개

삼성전자 DS부문 System LSI사업부는 Mobile Digital Life를 가능하게 하는 Mobile AP, CIS, Smart card, DDI 등에서 세계 1위를 달성하고 있는 명실상부한 국내 최대의 로직 반도체 업체입니다. System LSI사업부와 함께 진정한 글로벌 리더로 도약을 하고자 하는 우수 인재를 아래와 같이 모집합니다.

■ 지원기간

2012년 11월 8일(목) ~ 2012년 11월 18일(일) 22:00 限

■ 모집부문 및 주요업무

구 분	분 야	직 무 (주요업무)
Circuit Design	AP	<ul style="list-style-type: none"> - SOC Architecture design - ARM(AMBA) based SOC Integration - IP verification - Physical design(DFT, Synthesis, STA) - CPU/GPU Implementation, Design Methodology
	Wireless Connectivity (SOC/IP/RF)	<ul style="list-style-type: none"> - Chip architecture design - Logic design in RTL and simulation - Low power design implementation - Physical layer design for WLAN/Bluetooth - Communication Link layer design: WLAN MAC HW/FW, BT - Frequency synthesizer design: PLL/VCO/LO generator
	CIS (CMOS Image Sensor)	<ul style="list-style-type: none"> - Analog & Digital IC design - Pixel design - ISP development, CIS Evaluation
	PMIC (Power Management IC)	<ul style="list-style-type: none"> - PMIC Design(AP, Modem, battery chargers, battery management, a haptic motor driver IC, display applications) - Audio Amplifier and Codec Design
	DDI (Display Driver IC)	<ul style="list-style-type: none"> - Display Driver IC design for TFT-LCD / AMOLED - Verilog HDL Design for T-CON, High Speed Interface (MIPI/eDP) - High Speed/Low Power Design for Logic, Analog, Memory, IO Design - Touch controller SOC/Analog Sensing IC design
	Smart Card/MCU	<ul style="list-style-type: none"> - Analog & Digital IC design - Crypto, Secure driver, Secure OS(S/W) - NFC(Near Field Communication), eSE(embedded Secure Element), TPM(Trusted Platform Module)
Infra Design	Design Tech.	<ul style="list-style-type: none"> - Design Enabling(PDK, Modeling, Library IP, TCAD, etc) - Physical design methodology / DFM, DFT - Power & Signal integrity design methodology development - Low power, Timing Analysis design methodology development

	Mixed Signal Core / IP Development	<ul style="list-style-type: none"> - Mobile Analog(Termal/Power management IP) - Data converter(ADC, DAC) design - Clock Generator(PLL, DLL), Audio Codec design - Signal Process IP - Security IP - HSI PHY / LINK - Vedio Codec, ISP&Image Subsystem, 2/3D Graphics - Memory Subsystem, system interconnect - IP Verification, RTL/FPGA Verification
S/W	SOC (AP, Server. W/C)	<ul style="list-style-type: none"> - System S/W(Kernel & Device Driver, Firmware) - Middleware S/W(Multimedia Middleware, 2D/3D Graphics, HAL) - S/W Engineering(S/W development process improvement) - S/W Quality Engineering(S/W Quality Assurance, Integration & system Test)
Process Development	Advanced Logic Process Development & Integration	<ul style="list-style-type: none"> - SiO2/SiON Gate Dielectrics - High-K/Metal Gate - Etch/Thin Film/Lithography(including OPC/RET) - Silicide - Ultra Shallow Junction (including RTA & LSA) - Cu/Ultra Low-K - FEOL/BEOL Process Integration
	Device & Reliability Engineering	<ul style="list-style-type: none"> - Device & Reliability Engineering - Device Physics and Optimization - SRAM Development - Device Reliability (including BEOL reliability) - Strain / SPICE Modeling & Simulation
	기 타	<ul style="list-style-type: none"> - Defect & Yield Engineering - CMOS Image Sensor Development, Integration, Device & Analysis - Power Device Process Development, Integration, Device & Analysis
Process Technology	Yield Improvement	<ul style="list-style-type: none"> - Yield improvement & qualification of new process technology for production - Electrical data distribution improvement & ensure sufficient margin to prevent scraps - Identifying line excursion & root cause analysis with corrective and preventive action implemented
	Defect analysis	<ul style="list-style-type: none"> - Defect Inspection Tool Recipe Setup - Defect Monitoring System & Control t - Defect Analysis & Reduction - Surface & Organic Chemistry specialist(Pollution Analysis, Clean) - Advanced Data Engineering/Data mining, etc(Industrial engineering, Stastics major)
	Failure analysis	<ul style="list-style-type: none"> - SRAM & Logic Test - Device level analysis - Physical Failure Analysis Tool(TEM/SEM/FIB etc.)
Quality & Reliability	Quality & Reliability	<ul style="list-style-type: none"> - Process & Product Reliability Test and Qualification - Manufacturing Quality Methodology (SPC, SBL, FMEA, etc. set-up, execution & improve, MPQR check)

※ 근무지 : S.LSI사업부 기흥캠퍼스(경기도 용인시 소재)

■ 지원자격(공통사항)

- 박사 이상 학위 소지자로 관련부문 경력자(경력기간 무관) 및 졸업예정자('13.2月)
- 군필 및 면제자, 해외 여행에 결격사유가 없는 자(전문연구요원 전직 가능)

■ 지원방법

- www.samsungcareers.com - 경력채용 - [삼성전자]DS부문 S.LSI사업부 박사졸업자(졸업예정자)
채용공고 - 화면아래 "**지원**" 버튼 클릭 후 지원서 작성 - 새로운 이력서 작성
※ 본인이력 소개를 포함한 세부이력서 필히 첨부(첨부양식만 사용할 것)

■ 전형절차

지원서작성 » 지원서검토 » 면접전형 » 채용건진 » 최종합격

■ 기타

- 각종 증빙서류(어학, 학위, 경력관련 증명서) 제출은 별도안내 예정이며, 제출서류 중 허위기재 사실이 있는 경우에는 채용이 취소될 수 있습니다.
- 입사지원서 작성 시 전/현직 직장 및 회사의 영업, 연구비밀 등을 침해하지 않도록 유의 바랍니다.
- 문의처 : 삼성전자 S.LSI사업부 김성모 사원(smyo.kim@samsung.com)